Roll No. | | | | | | | | | | |

B.E / B.Tech (Full - Time) DEGREE END SEMESTER EXAMINATIONS, APRIL / MAY 2013

PRINTING TECHNOLOGY BRANCH
FOURTH SEMESTER

PT9254 OFFSET PLATEMAKING
(Regulation 2008)

Time: 3 Hours | Answer ALL Questions | Max. Marks 100

PART-A (10 x 2 = 20 Marks)

1. Compare the characteristic of half sheet and full sheet work.
2. Draw the folding scheme of concertina?
3. Write down the needs for metal key.
4. Which layout material do you recommend for colour brochure?
5. Give an example and the characteristic requirements of image and NI metals?
6. What is anodization process?
7. Define RIP? Brief the stages of it.
8. What do you mean by process less plates?
9. Differentiate between slur and doubling.
10. State any four important printing attribute.

Part – B (5 x 16 = 80 marks)

11. Discuss the working principle of any four important equipments used in plate making in detail

12. a) Explain the preparation and function of various types of burnout mask in detail.

OR

b) Discuss in detail about the preparation of any three methods used in negative flats assembly.

13. a) Using a neat diagram explain the working principle of direct and indirect method of electrostatic plate preparation.

OR

b) With the schematic diagram explain the various steps involved in the pre-preparation of offset plate manufacturing in detail

14. a) Explain the following.
i. Plates for digital imaging (8) ii. CTP workflow (8)

OR

b) Describe the working principle of various types of CTP system in detail with diagram.

15. a) i. Discuss the salient feature and purpose of different qc aids in UGRA plate control wedge. (10)
ii. Write a short note on test forms.(6)

OR

b) What is dot gain? Discuss the different variables that affect the dot gain and how to control it. (10)
ii. Write a short note on test forms.(6)